

HD74LS93

4-bit Binary Counter

REJ03D0423-0200 Rev.2.00 Feb.18.2005

The HD74LS93 contains four master-slave flip-flops and additional gating to provide a divide-by-two counter and three-state binary counter for divide-by-eight. To use this maximum count length of this counter, the B input is connected to the Q_A output. The input count pulses are applied to input A and the outputs are described in the appropriate function table.

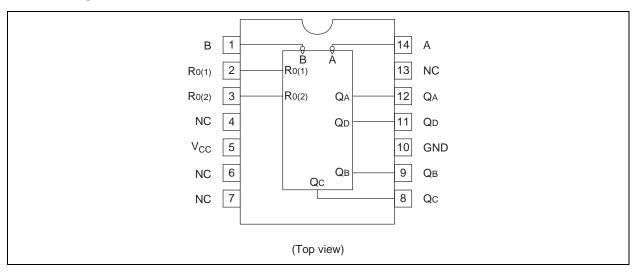
Features

• Ordering Information

Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74LS93P	DILP-14 pin	PRDP0014AB-B (DP-14AV)	Р	_
HD74LS93FPEL	SOP-14 pin (JEITA)	PRSP0014DF-B (FP-14DAV)	FP	EL (2,000 pcs/reel)

Note: Please consult the sales office for the above package availability.

Pin Arrangement



Function Table

• Reset / Count Function Table

Reset	eset inputs		Outputs				
R ₀₍₁₎	R ₀₍₂₎	Q_D	Q _C	Q _B	Q_A		
Н	Н	L	L	L	L		
L	Х	Count					
Х	L	Count					

Note: H; high level, L; low level, X; irrelevant

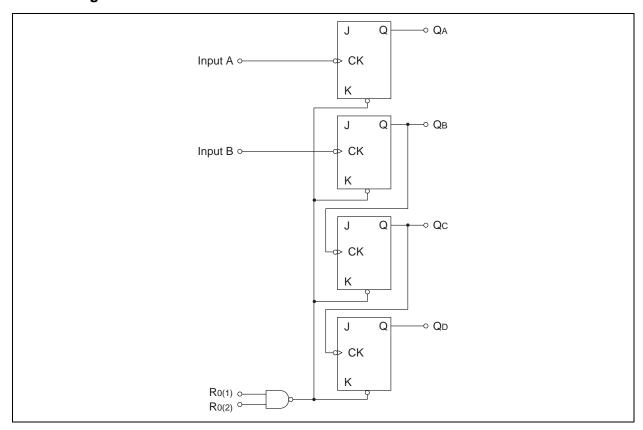
• BCD Count Sequence (Notes 1)

Count	Outputs						
	Q _D	Qc	Q _B	Q _A			
0	L	L	L	L			
1	L	L	L	Н			
2	L	L	Н	L			
3	L	L	Н	Н			
4	L	Н	L	Н			
5	L	Н	L	Н			
6	L	Н	Н	L			
7	L	Н	Н	Н			
8	Н	L	L	L			
9	Н	L	L	Н			
10	Н	L	Н	L			
11	Н	L	Н	Н			
12	Н	Н	L	L			
13	Н	Н	L	Н			
14	Н	Н	Н	L			
15	Н	Н	Н	Н			

Notes: 1. Output QA is connected to input B for BCD count.

2. H; high level, L; low level

Block Diagram



Absolute Maximum Ratings

Item		Symbol	Ratings	Unit
Supply voltage		V _{CC}	7	V
Input voltage	R Inputs	V _{IN}	7	V
Input voltage	A, B Inputs	V _{IN}	5.5	V
Power dissipation		P _T	400	mW
Storage temperature		Tstg	-65 to +150	°C

Note: Voltage value, unless otherwise noted, are with respect to network ground terminal.

Recommended Operating Conditions

Item		Symbol	Min	Тур	Max	Unit
Supply voltage		V _{CC}	4.75	5.00	5.25	V
Output current		I _{OH}	_	_	-400	μΑ
Output current		I _{OL}	_	_	8	mA
Operating temperature		Topr	-20	25	75	°C
0	A input		0	_	32	MHz
Count frequency	B input	f _{count}	0	_	16	IVITIZ
	A input		15	_	_	
Pulse width	B input	t_{w}	30	_	_	ns
	Reset input		15	_	_	
Setup time	•	t _{su}	25	_	_	ns

Electrical Characteristics

 $(Ta = -20 \text{ to } +75 \text{ }^{\circ}\text{C})$

	ltem	Symbol	min.	typ.*	max.	Unit	(Condition
Input voltage		V _{IH}	2.0	_	_	V		
Input voltage		V _{IL}	_	_	0.8	V		
		V _{OH}	2.7	_	_	V	$V_{CC} = 4.75 \text{ V}, V_{IH} = 2 \text{ V}, V_{IL} = 0.8 \text{ V},$ $I_{OH} = -400 \mu\text{A}$	
Output v	ollage	W	_	_	0.4	V		$V_{CC} = 4.75 \text{ V}, V_{IH} = 2 \text{ V},$
		V _{OL}	_	_	0.5	V	$I_{OL} = 8 \text{ mA**}$	$V_{IL} = 0.8 V$
	Any reset		_	_	-0.4		V _{CC} = 5.25 V, V _I = 0.4 V	
	A input	I _{IL}	_	_	-2.4	mA		
	B input		_	_	-1.6			
la a t	Any reset		_	_	20			
Input current	A input	I _{IH}	_	_	40	μΑ	$V_{CC} = 5.25 \text{ V}, \text{ V}_{I}$	= 2.7 V
Current	B input		_	_	40			
	Any reset		_	_	0.1		V _I = 7 V	
	A input	l _t	_	_	0.2	mA	V _I = 5.5 V	$V_{CC} = 5.25 \text{ V}$
	B input		_	_	0.2		V _I = 5.5 V	
Short-cir current	cuit output	Ios	-20	_	-100	mA	V _{CC} = 5.25 V	
Supply o	urrent	I _{CC} ***	_	9	15	mA	V _{CC} = 5.25 V	
Input cla	mp voltage	V _{IK}	_	_	-1.5	V	$V_{CC} = 4.75 \text{ V}, I_{IN}$	_I = -18 mA

Notes: $^*V_{CC} = 5 \text{ V}$, $Ta = 25^{\circ}C$

Switching Characteristics

 $(V_{CC} = 5 \text{ V}, \text{ Ta} = 25^{\circ}\text{C})$

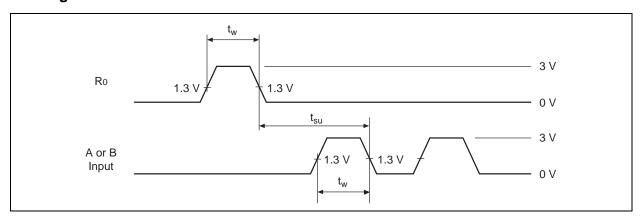
Item	Symbol	Inputs	Outputs	min.	typ.	max.	Unit	Condition
Maximum count frequency	f _{max}	Α	Q_A	32	42	_	MHz	
Maximum count frequency		В	Q _B	16	_	_	IVIITZ	
	t _{PLH}	А	Q_A	1	10	16		
	t _{PHL}	ζ	Q _A		12	18		
	t _{PLH}	А	Q _D	_	46	70		C_L = 15 pF, R_L = 2 k Ω
	t _{PHL}			1	46	70	ns	
	t _{PLH}	В	Q _B		10	16		
Propagation delay time	t _{PHL}	ם	QΒ		14	21		
	t _{PLH}	В	Qc		21	32		
	t _{PHL}	ь	Q _C	_	23	35		
	t _{PLH}	В	Q_D	_	34	51		
	t _{PHL}	D		_	34	51		
	t _{PHL}	Set-to-0	Q _A to Q _D		26	40		

Note: Refer to Test Circuit and Waveform of the Common Item "TTL Common Matter (Document No.: REJ27D0005-0100)".

^{**} Q_A output is tested at specified I_{OL} plus the limit value of IIL for the B input. This permits driving the B input while maintaining full fan-out capability.

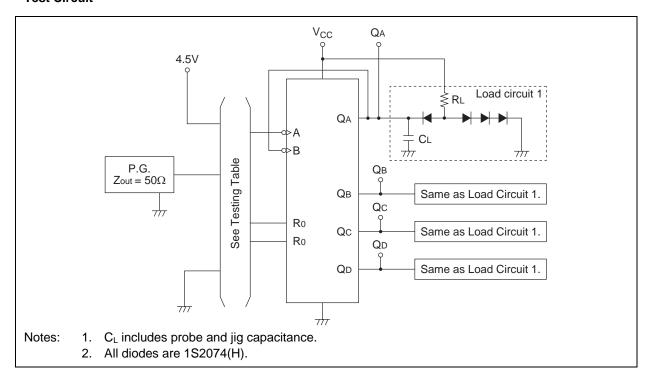
^{***} I_{CC} is measured with all outputs open, both R_0 inputs grounded following momentary connection to 4.5 V, and all other inputs grounded.

Timing Definition



Testing Method

Test Circuit



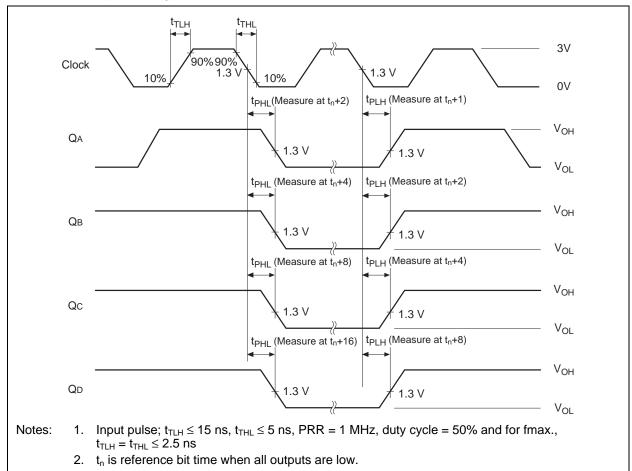
Testing Table

Item	From input		Inputs		Outputs			
item	to output	Α	В	R ₀	Q _A	Q _B	Q _C	Q_D
f _{max}	$A\toQ$	IN	to Q _A	GND	Out	Out	Out	Out
Imax	$B\toQ$	4.5 V	IN	GND	_	Out	Out	Out
	$A\toQ_A$	IN	to Q _A	GND	Out	_	_	
	$A\toQ_D$	IN	to Q _A	GND	_	_	_	Out
t _{PLH}	$B\toQ_B$	4.5 V	IN	GND	_	Out	_	_
t _{PHL}	$B\toQ_C$	4.5 V	IN	GND	_	_	Out	_
	$B\toQ_D$	4.5 V	IN	GND	_	_	_	Out
	$R_0^{**} \rightarrow Q$	IN*	to Q _A	IN	Out	Out	Out	Out

^{*} For initialized.

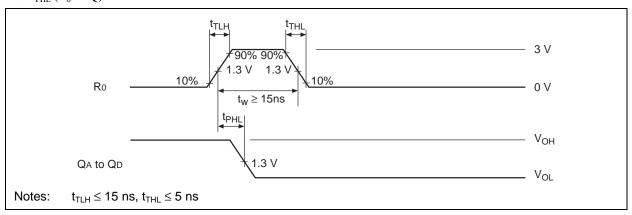
Waveform

1. f_{max} , t_{PLH} , t_{PHL} (Clock \rightarrow Q)

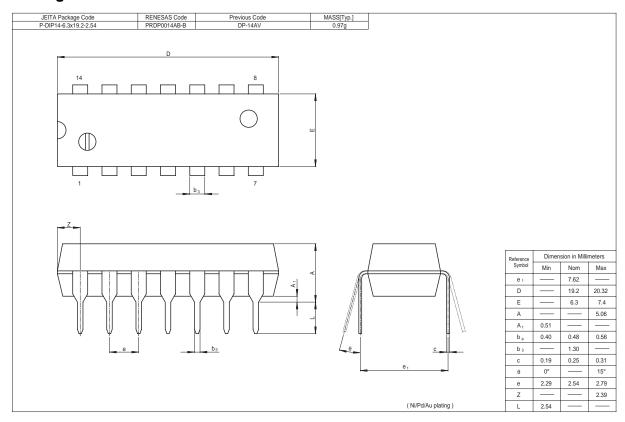


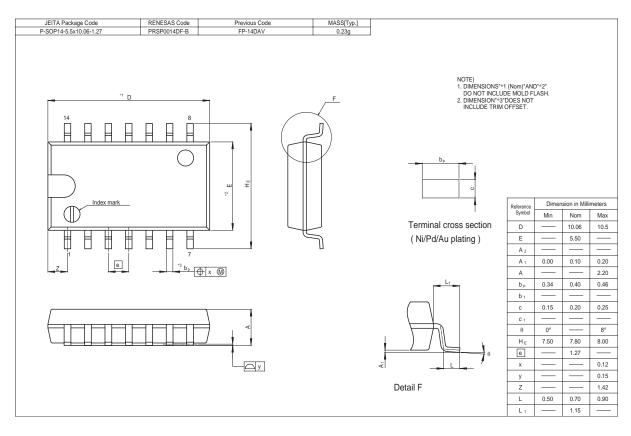
^{**} Measured with each input and unused inputs at 4.5 V.

2. $t_{PHL} (R_0 \rightarrow Q)$



Package Dimensions





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